


Full Material Declaration for attached parts list

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	<p>Diotec Semiconductor AG DUNS number: 330866844 -, Kreuzmattenstr. 4, Heitersheim, B.-W., 79423, Germany Declarations authorised by Udo Steinebrunner, Product Manager, -</p>
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Declaration effective from: 01 May 2009 [Approved: 31 January 2025 14:43 GMT]

Individual materials in the part			Individual substances in each material		
Use/Location	Material Group	Max mass %	Substance	CAS Number	Max mass %
Attach agent	Other nonferrous metals	0.5%	Formaldehyde, polymer with (chloromethyl)oxirane and phenol	9003-36-5	8.5%
			2,3-EPOXYPROPYL-4-T-BUTYLPHENYL ETHER	3101-60-8	9.5%
			SILVER, ELEMENTAL	7440-22-4	82%
Chip (die)	Other inorganic materials	0.25%	Elemental silicon	7440-21-3	100%
			Carbon black	1333-86-4	0.8%
			Silicon Dioxide	7631-86-9	2.5%
			Phenol, polymer with formaldehyde	9003-35-4	3.7%
Encapsulation	EP (Epoxy resin)	68.52%	Aluminum hydroxide (Al(OH) ₃)	21645-51-2	5%
			Formaldehyde, polymer with (chloromethyl)oxirane and 2-methylphenol	29690-82-2	6%
			Quartz sand	60676-86-0	82%
Inner preparation	Copper (e.g. copper amounts in cable harnesses)	0.17%	COPPER, ELEMENTAL	7440-50-8	100%
Leadfinish	Tin plating	1.6%	Tin	7440-31-5	100%
			Copper	7440-50-8	0.168%
Leadframe	Copper (e.g. copper amounts in cable harnesses)	28.96%	SILVER, ELEMENTAL	7440-22-4	1.196%
			Iron nickel zinc oxide REACH Article 67 Exemption	12645-50-0	98.636%

Attached parts list

Part number	Part name
SOT-323 (H) Pb&H-Free_Cu_Ag-glue	Diode / Transistor SMD